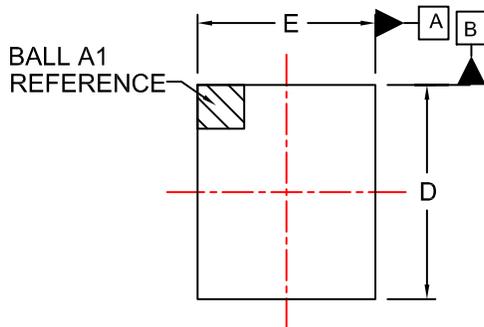




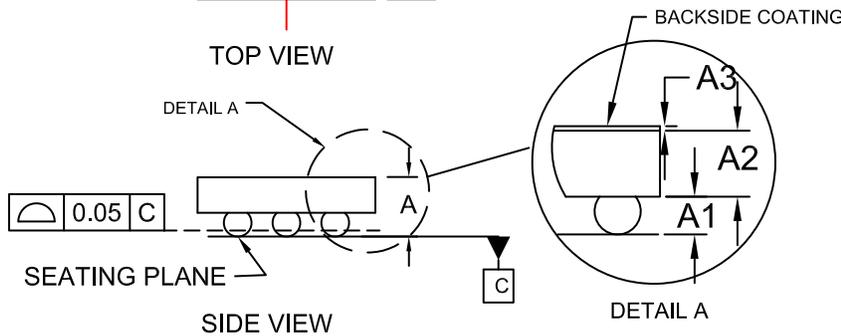
WLCSP12 1.620x1.635x0.457
CASE 567ZW
ISSUE O

DATE 06 JAN 2021

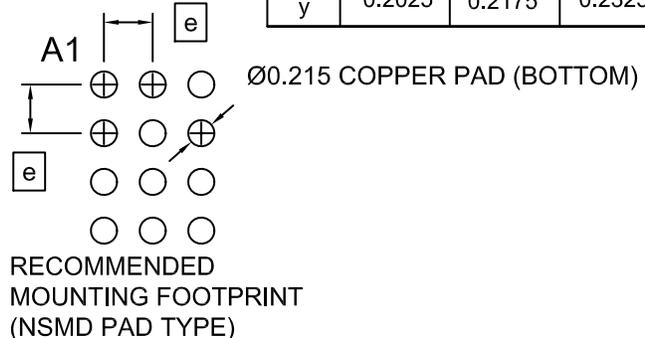
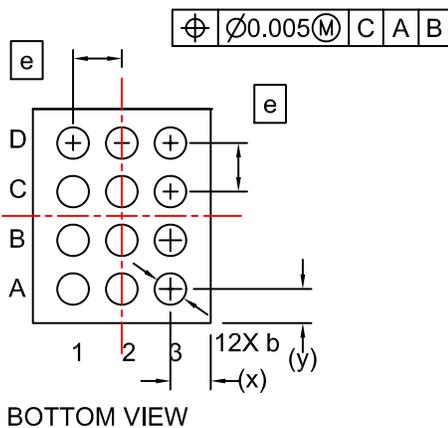


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DATUM C APPLIES TO THE SPHERICAL CROWN OF THE SOLDER BALLS



DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.416	0.457	0.498
A1	0.183	0.203	0.223
A2	0.211	0.229	0.247
A3	0.022	0.025	0.028
b	0.240	0.260	0.280
D	1.605	1.635	1.665
E	1.590	1.620	1.650
e	0.40 BSC		
x	0.395	0.410	0.425
y	0.2025	0.2175	0.2325



*For additional information on our Pb-Free strategy and soldering details, please download the On Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



XXXX = Specific Device Code
A = Assembly Location
YY = Year
WW = Work Week

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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